CUI DEVICES

MODEL: HSB15-404010 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



RoHS

MODEL

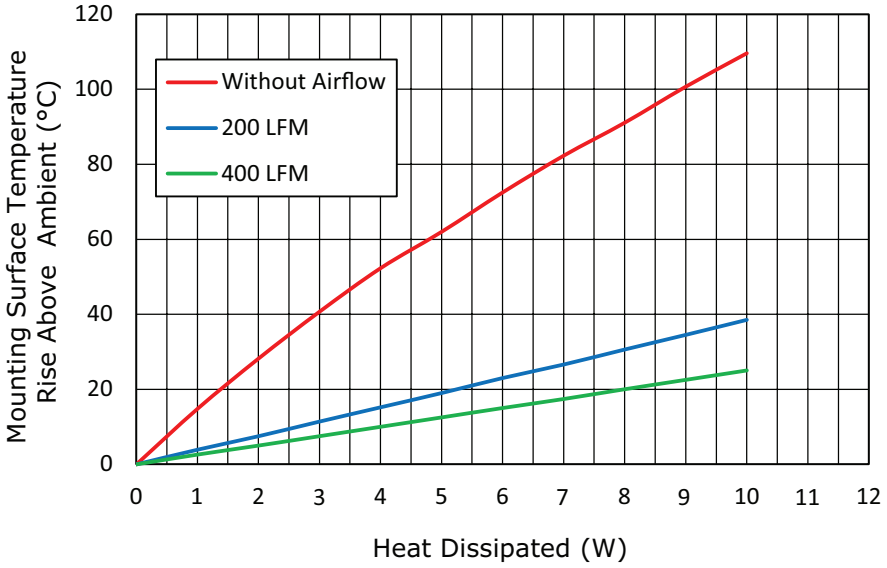
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB15-404010	11.84	14.8	3.9	2.6	6.33

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	14.8	3.9	2.6
2	28.2	7.5	5.0
3	40.7	11.4	7.5
4	52.3	15.2	10.0
5	62.0	19.0	12.5
6	72.5	23.0	15.0
7	82.3	26.6	17.4
8	91.1	30.6	20.0
9	100.7	34.5	22.5
10	109.6	38.5	25.0

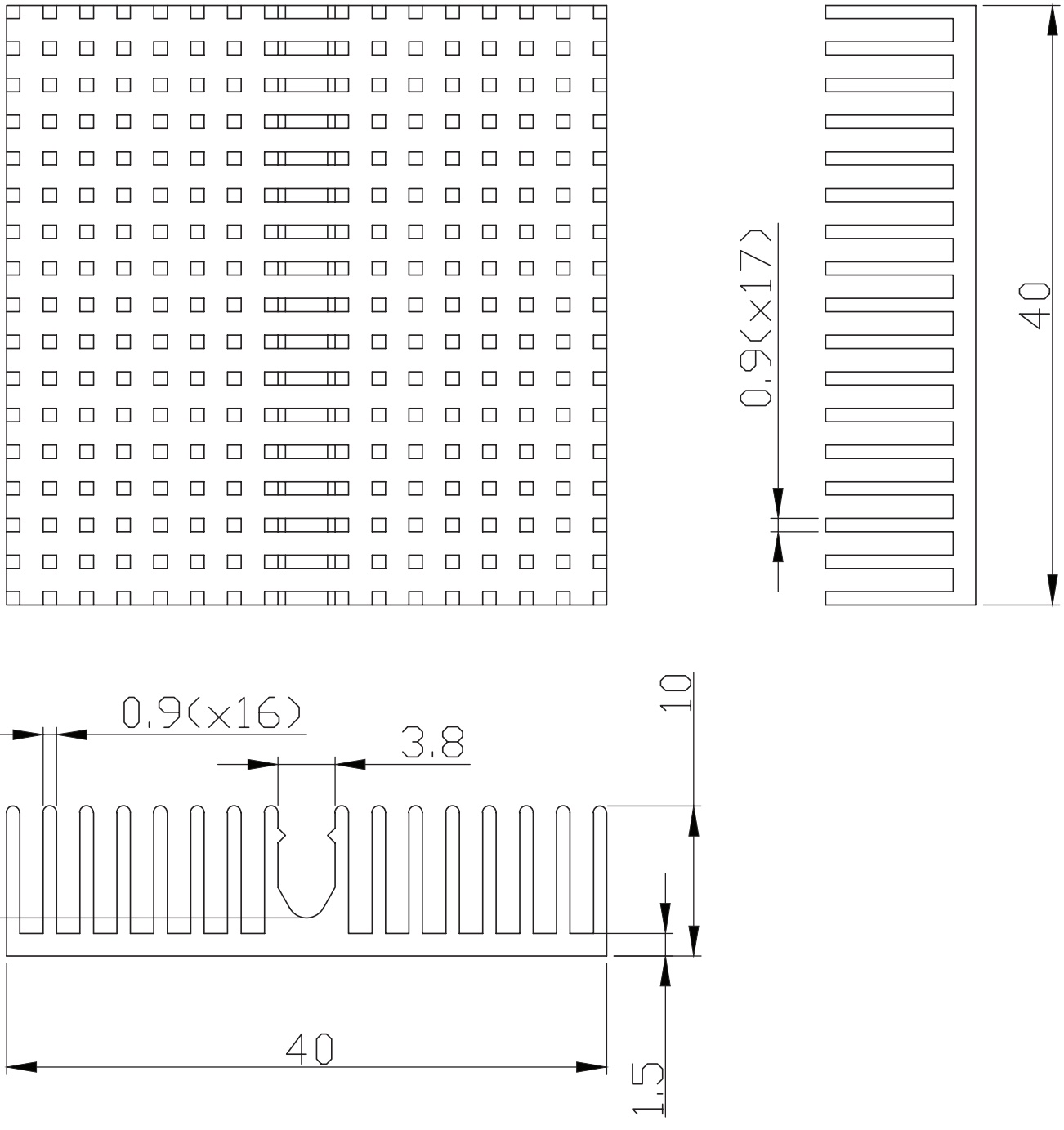
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	15.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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